

ABSTRACT

The present invention provides a nonwoven fabric material prepared from short fibers including thermal-resistant synthetic fibers bound with an inorganic binder, a prepreg and a circuit board using the same. The circuit board has an excellent dimensional stability even at a high temperature, and the circuit board is prevented from warping or being damaged by moisture absorption or the like. The inorganic binder is a residue formed from a low melting point glass solution or a water-dispersible colloidal solution including at least either fibers or particles of low melting point glass dispersed therein. When the binder is used, a chemical covalent bonding by a siloxane bonding is formed.

"Express Mail" mailing label number EL435546910US

Date of Deposit FEBRUARY 17, 2000

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231

LINDA MCCORMICK

printed name

Linda McCormick

Signature